



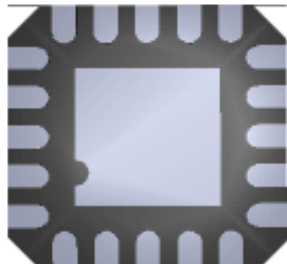
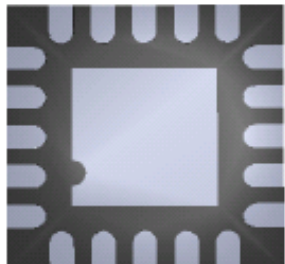


Bill of Materials and Package Configuration

Material	FROM	TO	Remarks
	Amkor - Korea	Amkor - Philippines	
Die Attach	Ablestik 8290	Ablestik 3230	Same Resin Base
Wire	Au	Au	Same
Mold Compound	Sumitomo G700	Sumitomo G700	Same
Leadframe	C194	C194	Same
Package: Side			Punch: Flange Sawn: Square
Top			Sawn: • Pin 1 is Laser Marked • Square Edge
Bottom			Same Foot Print

Package Dimensions

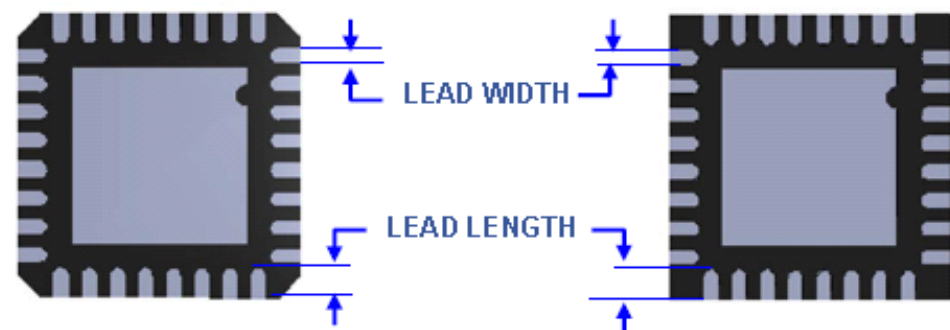
PUNCH



SAWN



Package Thickness Difference



Exposed Pad, Lead Length and Lead Width dimensions remains within tolerance.

Body Size (mm)	Lead Count	Lead Pitch (mm)	Punch LFCSP POD	Sawn LFCSP POD	Exposed Pad Size (mm)
5 x 5	16	0.8	CP 16-6	CP 16-31	3.1 x 3.1
	20	0.65	CP 20-5	CP 20-9	3.1 x 3.1
	32	0.5	CP 32-8	CP 32-21	2.7 x 2.7
			CP 32-2	CP 32-7	3.1 x 3.1
			CP 32-3	CP 32-13	3.3 x 3.3
			CP 32-4	CP 32-11	3.5 x 3.5

Qualification Results Summary of Sawn LFCSP Package at Amkor Philippines (ATP)

QUALIFICATION RESULTS			
Test	Conditions	Sample Size	Results
Temperature/Humidity Biase (THB)*	JEDEC JESD22-A101	3 x 77	Passed
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	Passed
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	Passed
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Passed
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	3 x 77	Passed
Field-Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	1 x 18	Passed

* These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C. TC samples were subjected to wire-pull test after 500 cycles with results within specification limits.